

NCE Automotive N-Channel Enhancement Mode Power MOSFET

Description

The NCEA75H25 uses advanced trench technology and design to provide excellent $R_{\text{DS(ON)}}$ with low gate charge. It can be used in a wide variety of applications.

Application

- Automotive application
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

General Features

V_{DS} = 75V,I_D =250A

 $R_{DS(ON)}$ <3.0m Ω @ V_{GS} =10V (Typ:2.5m Ω)

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS
- Excellent package for good heat dissipation
- 175 °C operating temperature
- Pb-free lead plating;RoHScompliant
- Halogen-freeaccording to IEC61249-2-21
- 100% UIS tested
- 100% ΔVds tested
- AEC-Q101 qualified

TO-220-3L





Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
A75H25	NCEA75H25	TO-220-3L	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	75	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	250	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	177	Α
Pulsed Drain Current	I _{DM}	1000	Α
Maximum Power Dissipation	P _D	371	W
Derating factor		2.47	W/°C
Single pulse avalanche energy (Note 1)	E _{AS}	2880	mJ
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 175	$^{\circ}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case	ReJc	0.40	°C/W
Thermal Resistance, Junction-to-Ambient (Note 4)	Reja	40	°C/W



Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	75	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1	1.5	2	V
Dunin Course On Otata Basistana	Б	V _{GS} =10V, I _D =20A	-	2.5	3	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	3.5	4.2	mΩ
Forward Transconductance	g FS	V _{DS} =20V,I _D =20A	-	70	-	S
Dynamic Characteristics						
Input Capacitance	C _{lss}	V _{DS} =35V,V _{GS} =0V,	-	14722	-	pF
Output Capacitance	Coss		-	1012	-	pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	883	-	pF
Switching Characteristics (Note 2)						
Turn-on Delay Time	t _{d(on)}		-	26	-	nS
Turn-on Rise Time	tr	V_{DD} =35 V , R_L =1 Ω	-	69	-	nS
Turn-Off Delay Time	t _{d(off)}	$V_{\text{GS}}\text{=}10V, R_{\text{GEN}}\text{=}2.5\Omega$	-	128	-	nS
Turn-Off Fall Time	t _f		-	40	-	nS
Total Gate Charge	Qg	V _{DS} =35V,I _D =20A,	-	311	-	nC
Gate-Source Charge	Qgs		-	40.5	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	77	-	nC
Drain-Source Diode Characteristics	,					
Diode Forward Voltage	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current	Is	-	-	-	250	Α
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 20A	-	96	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs	-	380	-	nC

Notes:

- 1. EAS condition : Tj=25 $^{\circ}\text{C}\text{,V}_{DD}\text{=}40\text{V,V}_{G}\text{=}10\text{V,L=}0.5\text{mH,Rg=}25\Omega$
- 2. Guaranteed by design, not subject to production
- 3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C. The SOA curve provides a single pulse rating.
- 4.The value of R_{BJA} is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_{A} =25° C. The maximum allowed junction temperature of 175° C. The value in any given application depends on the user's specific board design.



Typical Electrical and Thermal Characteristics (Curves)

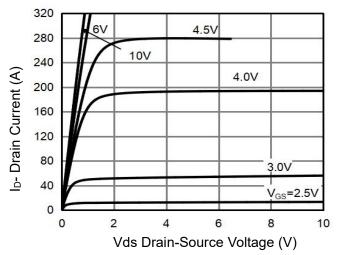


Figure 1 Output Characteristics

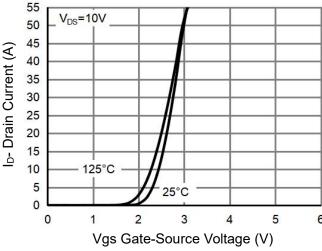


Figure 2 Transfer Characteristics

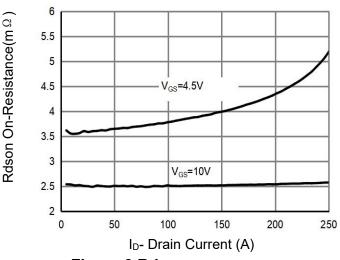


Figure 3 Rdson- Drain Current

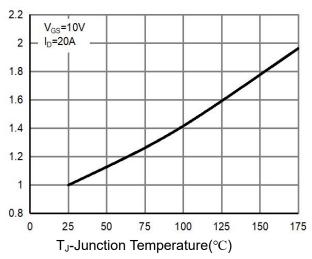


Figure 4 Rdson-JunctionTemperature

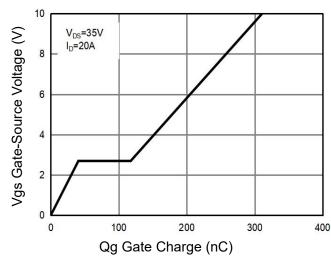


Figure 5 Gate Charge

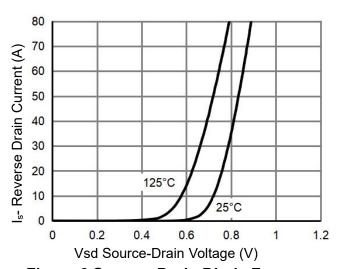
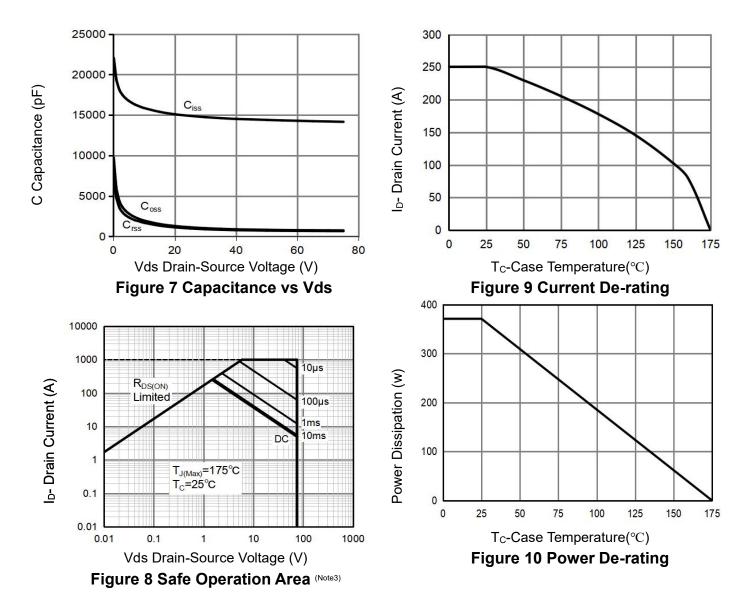


Figure 6 Source- Drain Diode Forwar





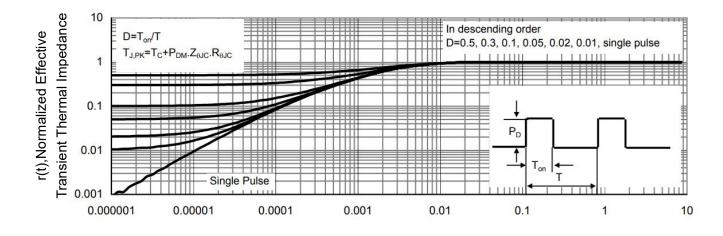
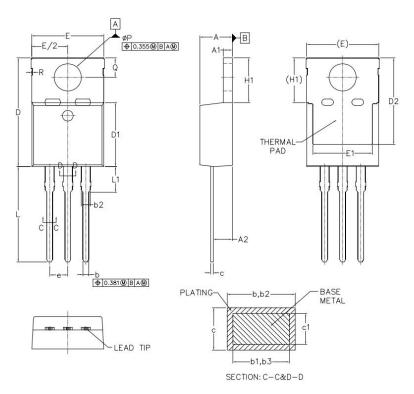


Figure 11 Normalized Maximum Transient Thermal Impedance

Square Wave Pluse Duration(sec)



TO-220-3L Package Information



Ş	COMMON			
	ММ			
MBOLIN	MIN.	MAX.		
Α	3.556	4.826		
A1	0.508	1.397		
A2	2.032	2.921		
ь	0.381	1.016		
b1	0.381	0.965		
b2	1.143	1.778		
b3	1.143	1.727		
С	0.356	0.610		
с1	0.356	0.559		
D	14.224	16.510		
D1	8.382	9.017		
D2	12.042	12.878		
E	9.652	10.668		
E1	6.858	8.890		
е	2.540	2.540 BSC.		
H1	5.842	6.858		
L	12.700	14.732		
L1	3.560	4.060		
ØΡ	3.810	3.860		
Q	2.540	3.048		
R	0.127 BSC			



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